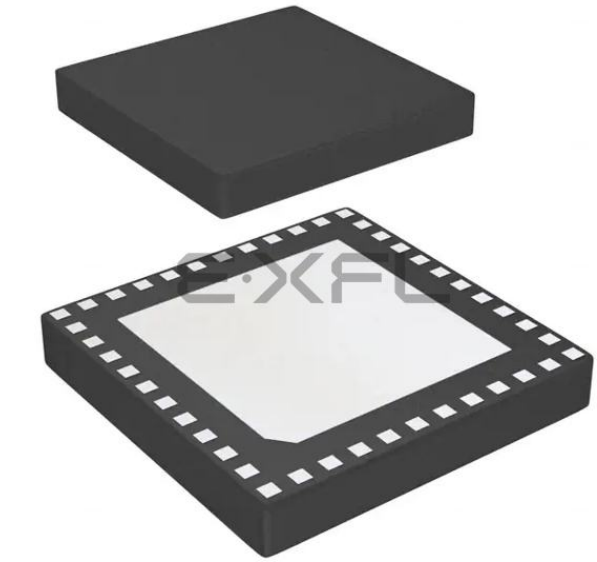
Microchip Technology - PIC32MX130F064DT-V/TL Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx130f064dt-v-tl

TABLE 4: PIN NAMES FOR 28-PIN USB DEVICES

28-PIN SOIC, SPDIP, SSOP (TOP VIEW)(1,2,3)

PIC32MX210F016B
PIC32MX220F032B
PIC32MX230F064B
PIC32MX230F256B
PIC32MX250F128B
PIC32MX270F256B

Pin #	Full Pin Name	Pin #	Full Pin Name
1	$\overline{\text{MCLR}}$	15	V_{BUS}
2	PGED3/V_{REF}+/CV_{REF}+/AN0/C3INC/RPA0/CTED1/PMD7/RA0	16	TDI/RPB7/CTED3/PMD5/INT0/RB7
3	PGEC3/V_{REF}-/CV_{REF}-/AN1/RPA1/CTED2/PMD6/RA1	17	TCK/RPB8/SCL1/CTED10/PMD4/RB8
4	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	18	TDO/RPB9/SDA1/CTED4/PMD3/RB9
5	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	19	V_{SS}
6	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	20	V_{CAP}
7	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	21	PGED2/RPB10/D+/CTED11/RB10
8	V_{SS}	22	PGEC2/RPB11/D-/RB11
9	OSC1/CLKI/RPA2/RA2	23	V_{USB3V3}
10	OSC2/CLKO/RPA3/PMA0/RA3	24	AN11/RPB13/CTPLS/PMRD/RB13
11	SOSCI/RPB4/RB4	25	CV_{REFOUT}/AN10/C3INB/RPB14/V_{BUSON}/SCK1/CTED5/RB14
12	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	26	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
13	V_{DD}	27	AV_{SS}
14	TMS/RPB5/USBID/RB5	28	AV_{DD}

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

TABLE 10: PIN NAMES FOR 44-PIN USB DEVICES

44-PIN QFN (TOP VIEW)(1,2,3,5)

PIC32MX210F016D
PIC32MX220F032D
PIC32MX230F064D
PIC32MX230F256D
PIC32MX250F128D
PIC32MX270F256D

44 1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMD3/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3
3	RPC7/PMA0/RC7	25	AN6/RPC0/RC0
4	RPC8/PMA5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMA6/RC9	27	AN8/RPC2/PMA2/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED2/RPB10/D+/CTED11/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC2/RPB11/D-/RB11	31	OSC2/CLKO/RPA3/RA3
10	VUSB3V3	32	TDO/RPA8/PMA8/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/RB4
12	PGED4/TMS/PMA10/RA10	34	SOSCO/RPA4/T1CK/CTED9/RA4
13	PGEC4/TCK/CTED8/PMA7/RA7	35	TDI/RPA9/PMA9/RA9
14	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14	36	AN12/RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	37	RPC4/PMA4/RC4
16	AVSS	38	RPC5/PMA3/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0	41	RPB5/USBID/RB5
20	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1	42	VBUS
21	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	43	RPB7/CTED3/PMD5/INT0/RB7
22	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	44	RPB8/SCL1/CTED10/PMD4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

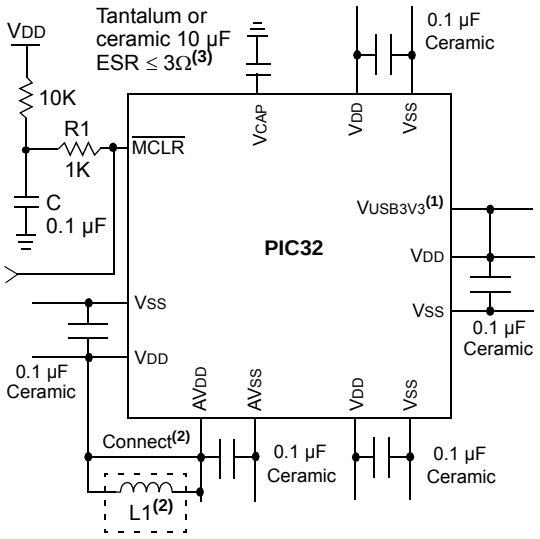
2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX110F016D and PIC32MX120F032D devices.

5: Shaded pins are 5V tolerant.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: If the USB module is not used, this pin must be connected to VDD.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

1: Aluminum or electrolytic capacitors should not be used. ESR ≤ 3Ω from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (3 ohm) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a CEFC capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **30.0 "Electrical Characteristics"** for additional information on CEFC specifications.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

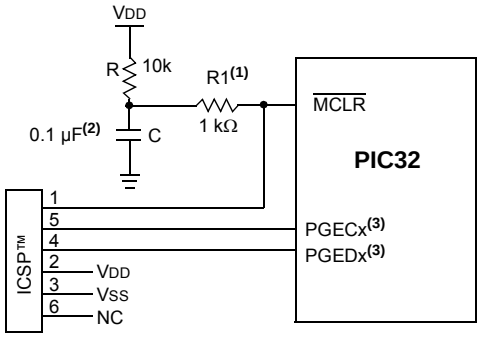
- Device Reset
- Device programming and debugging

Pulling The MCLR pin low generates a device Reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: 470Ω ≤ R1 ≤ 1Ω will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met without interfering with the Debug/Programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

3.0 CPU

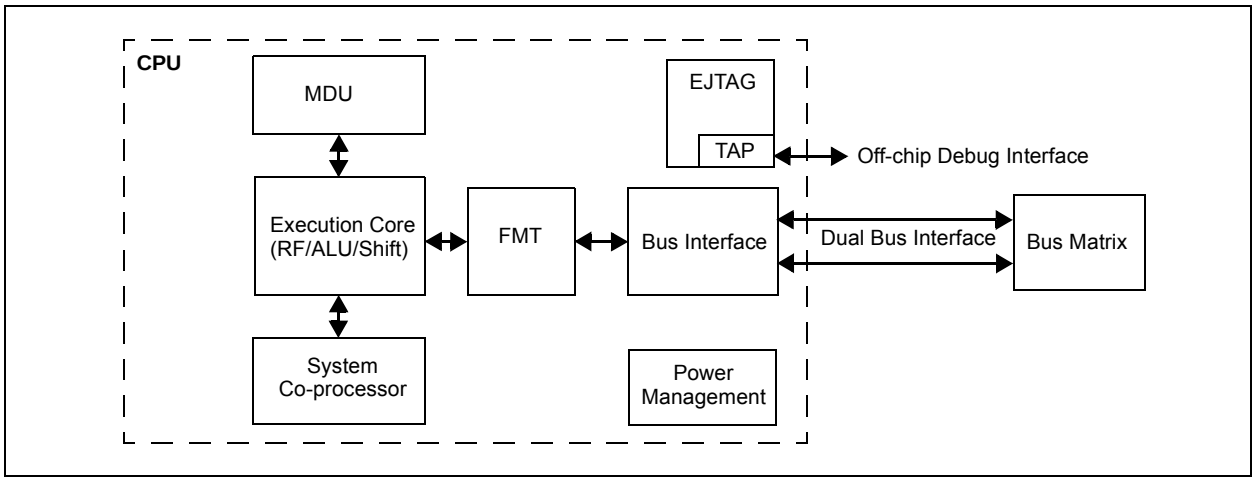
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 2. "CPU"** (DS60001113), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32). Resources for the MIPS32® M4K® Processor Core are available at: www.imgtec.com.

The MIPS32® M4K® Processor Core is the heart of the PIC32MX1XX/2XX family processor. The CPU fetches instructions, decodes each instruction, fetches source operands, executes each instruction and writes the results of instruction execution to the destinations.

3.1 Features

- 5-stage pipeline
- 32-bit address and data paths
- MIPS32 Enhanced Architecture (Release 2)
  - Multiply-accumulate and multiply-subtract instructions
  - Targeted multiply instruction
  - Zero/One detect instructions
  - `WAIT` instruction
  - Conditional move instructions (`MOVN`, `MOVZ`)
  - Vectored interrupts
  - Programmable exception vector base
  - Atomic interrupt enable/disable
  - Bit field manipulation instructions
- MIPS16e® code compression
  - 16-bit encoding of 32-bit instructions to improve code density
  - Special PC-relative instructions for efficient loading of addresses and constants
  - `SAVE` and `RESTORE` macro instructions for setting up and tearing down stack frames within subroutines
  - Improved support for handling 8 and 16-bit data types
- Simple Fixed Mapping Translation (FMT) mechanism
- Simple dual bus interface
  - Independent 32-bit address and data buses
  - Transactions can be aborted to improve interrupt latency
- Autonomous multiply/divide unit
  - Maximum issue rate of one 32x16 multiply per clock
  - Maximum issue rate of one 32x32 multiply every other clock
  - Early-in iterative divide. Minimum 11 and maximum 33 clock latency (dividend (*rs*) sign extension-dependent)
- Power control
  - Minimum frequency: 0 MHz
  - Low-Power mode (triggered by `WAIT` instruction)
  - Extensive use of local gated clocks
- EJTAG debug and instruction trace
  - Support for single stepping
  - Virtual instruction and data address/value
  - Breakpoints

FIGURE 3-1: MIPS32® M4K® PROCESSOR CORE BLOCK DIAGRAM



3.2 Architecture Overview

The MIPS32 M4K processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32 M4K processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32 M4K processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the *rs* operand. The second number ('16' of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

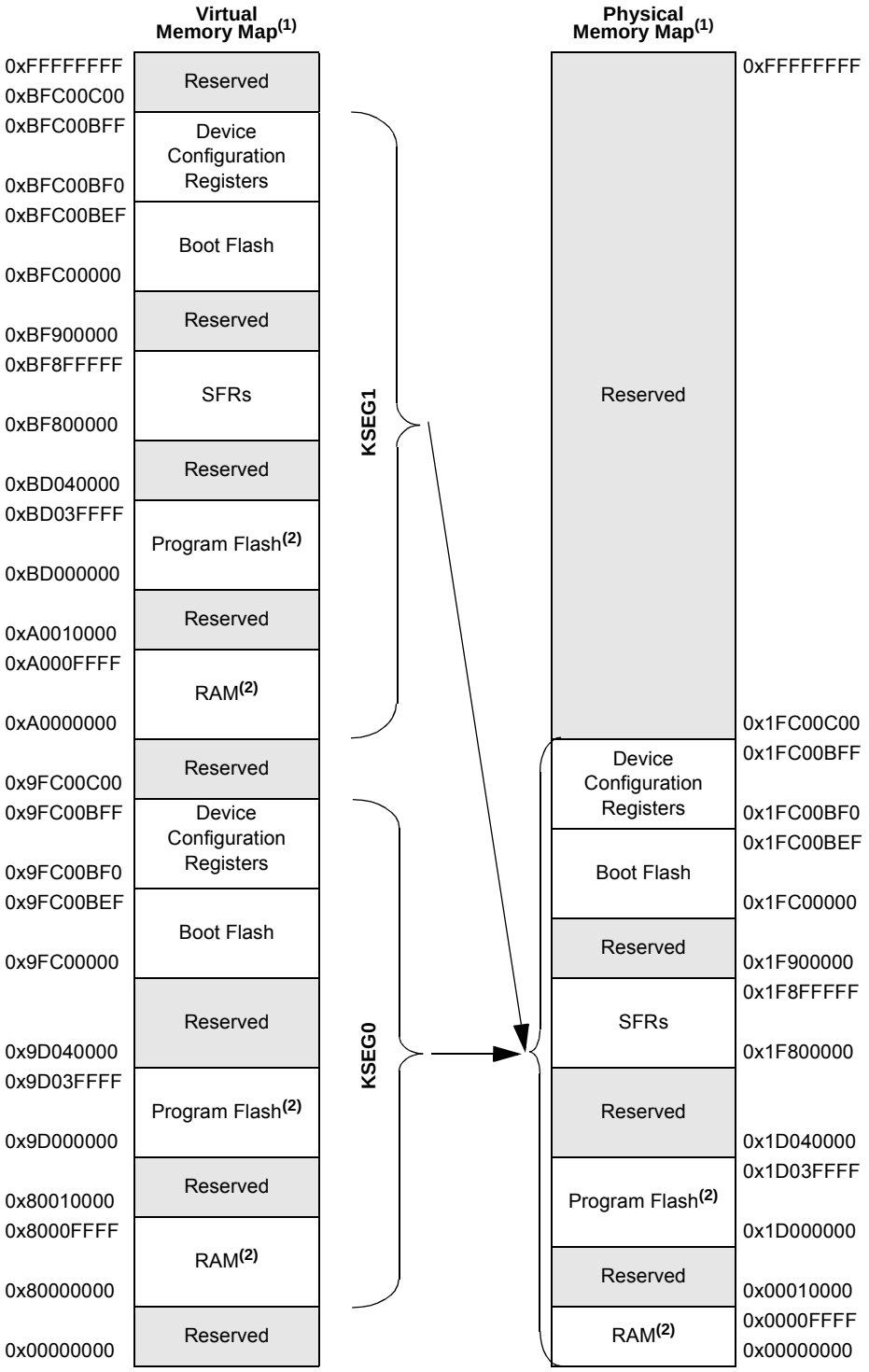
Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL`	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

FIGURE 4-5: MEMORY MAP ON RESET FOR PIC32MX170/270 DEVICES (64 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

TABLE 7-1: INTERRUPT IRQ, VECTOR AND BIT LOCATION (CONTINUED)

Interrupt Source(1)	IRQ #	Vector #	Interrupt Bit Location				Persistent Interrupt
			Flag	Enable	Priority	Sub-priority	
U1E – UART1 Fault	39	32	IFS1<7>	IEC1<7>	IPC8<4:2>	IPC8<1:0>	Yes
U1RX – UART1 Receive Done	40	32	IFS1<8>	IEC1<8>	IPC8<4:2>	IPC8<1:0>	Yes
U1TX – UART1 Transfer Done	41	32	IFS1<9>	IEC1<9>	IPC8<4:2>	IPC8<1:0>	Yes
I2C1B – I2C1 Bus Collision Event	42	33	IFS1<10>	IEC1<10>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1S – I2C1 Slave Event	43	33	IFS1<11>	IEC1<11>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1M – I2C1 Master Event	44	33	IFS1<12>	IEC1<12>	IPC8<12:10>	IPC8<9:8>	Yes
CNA – PORTA Input Change Interrupt	45	34	IFS1<13>	IEC1<13>	IPC8<20:18>	IPC8<17:16>	Yes
CNB – PORTB Input Change Interrupt	46	34	IFS1<14>	IEC1<14>	IPC8<20:18>	IPC8<17:16>	Yes
CNC – PORTC Input Change Interrupt	47	34	IFS1<15>	IEC1<15>	IPC8<20:18>	IPC8<17:16>	Yes
PMP – Parallel Master Port	48	35	IFS1<16>	IEC1<16>	IPC8<28:26>	IPC8<25:24>	Yes
PMPE – Parallel Master Port Error	49	35	IFS1<17>	IEC1<17>	IPC8<28:26>	IPC8<25:24>	Yes
SPI2E – SPI2 Fault	50	36	IFS1<18>	IEC1<18>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2RX – SPI2 Receive Done	51	36	IFS1<19>	IEC1<19>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2TX – SPI2 Transfer Done	52	36	IFS1<20>	IEC1<20>	IPC9<4:2>	IPC9<1:0>	Yes
U2E – UART2 Error	53	37	IFS1<21>	IEC1<21>	IPC9<12:10>	IPC9<9:8>	Yes
U2RX – UART2 Receiver	54	37	IFS1<22>	IEC1<22>	IPC9<12:10>	IPC9<9:8>	Yes
U2TX – UART2 Transmitter	55	37	IFS1<23>	IEC1<23>	IPC9<12:10>	IPC9<9:8>	Yes
I2C2B – I2C2 Bus Collision Event	56	38	IFS1<24>	IEC1<24>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2S – I2C2 Slave Event	57	38	IFS1<25>	IEC1<25>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2M – I2C2 Master Event	58	38	IFS1<26>	IEC1<26>	IPC9<20:18>	IPC9<17:16>	Yes
CTMU – CTMU Event	59	39	IFS1<27>	IEC1<27>	IPC9<28:26>	IPC9<25:24>	Yes
DMA0 – DMA Channel 0	60	40	IFS1<28>	IEC1<28>	IPC10<4:2>	IPC10<1:0>	No
DMA1 – DMA Channel 1	61	41	IFS1<29>	IEC1<29>	IPC10<12:10>	IPC10<9:8>	No
DMA2 – DMA Channel 2	62	42	IFS1<30>	IEC1<30>	IPC10<20:18>	IPC10<17:16>	No
DMA3 – DMA Channel 3	63	43	IFS1<31>	IEC1<31>	IPC10<28:26>	IPC10<25:24>	No
Lowest Natural Order Priority							

Note 1: Not all interrupt sources are available on all devices. See **TABLE 1: "PIC32MX1XX 28/36/44-Pin General Purpose Family Features"** and **TABLE 2: "PIC32MX2XX 28/36/44-pin USB Family Features"** for the lists of available peripherals.

8.0 OSCILLATOR CONFIGURATION

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 6. "Oscillator Configuration"** (DS60001112), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX1XX/2XX 28/36/44-pin Family oscillator system has the following modules and features:

- Four external and internal oscillator options as clock sources
- On-Chip PLL with user-selectable input divider, multiplier and output divider to boost operating frequency on select internal and external oscillator sources
- On-Chip user-selectable divisor postscaler on select oscillator sources
- Software-controllable switching between various clock sources
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Dedicated On-Chip PLL for USB peripheral

A block diagram of the oscillator system is provided in Figure 8-1.

REGISTER 10-3: U1OTGSTAT: USB OTG STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-0	U-0	R-0	U-0	R-0	R-0	U-0	R-0
	ID	—	LSTATE	—	SESVD	SESEND	—	VBUSVD

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **ID:** ID Pin State Indicator bit
- 1 = No cable is attached or a "type B" cable has been inserted into the USB receptacle
- 0 = A "type A" OTG cable has been inserted into the USB receptacle

bit 6 **Unimplemented:** Read as '0'

bit 5 **LSTATE:** Line State Stable Indicator bit
- 1 = USB line state (SE0 (U1CON<6>) bit and JSTATE (U1CON<7>)) bit has been stable for previous 1 ms
- 0 = USB line state (SE0 and JSTATE) has not been stable for previous 1 ms

bit 4 **Unimplemented:** Read as '0'

bit 3 **SESVD:** Session Valid Indicator bit
- 1 = VBUS voltage is above Session Valid on the A or B device
- 0 = VBUS voltage is below Session Valid on the A or B device

bit 2 **SESEND:** B-Device Session End Indicator bit
- 1 = VBUS voltage is below Session Valid on the B device
- 0 = VBUS voltage is above Session Valid on the B device

bit 1 **Unimplemented:** Read as '0'

bit 0 **VBUSVD:** A-Device VBUS Valid Indicator bit
- 1 = VBUS voltage is above Session Valid on the A device
- 0 = VBUS voltage is below Session Valid on the A device

TABLE 11-6: PERIPHERAL PIN SELECT INPUT REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FA04	INT1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	INT1R<3:0>				0000
FA08	INT2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	INT2R<3:0>				0000
FA0C	INT3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	INT3R<3:0>				0000
FA10	INT4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	INT4R<3:0>				0000
FA18	T2CKR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	T2CKR<3:0>				0000
FA1C	T3CKR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	T3CKR<3:0>				0000
FA20	T4CKR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	T4CKR<3:0>				0000
FA24	T5CKR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	T5CKR<3:0>				0000
FA28	IC1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC1R<3:0>				0000
FA2C	IC2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC2R<3:0>				0000
FA30	IC3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC3R<3:0>				0000
FA34	IC4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC4R<3:0>				0000
FA38	IC5R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC5R<3:0>				0000
FA48	OCFAR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	OCFAR<3:0>				0000
FA4C	OCFBR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	OCFBR<3:0>				0000
FA50	U1RXR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U1RXR<3:0>				0000

REGISTER 11-1: [*pin name*]R: PERIPHERAL PIN SELECT INPUT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	[*pin name*]R<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-4 **Unimplemented:** Read as '0'

bit 3-0 **[*pin name*]R<3:0>:** Peripheral Pin Select Input bits
Where [*pin name*] refers to the pins that are used to configure peripheral input mapping. See Table 11-1 for input pin selection values.

Note: Register values can only be changed if the Configuration bit, IOLOCK (CFGCON<13>), = 0.

REGISTER 11-2: RPnR: PERIPHERAL PIN SELECT OUTPUT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	RPnR<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-4 **Unimplemented:** Read as '0'

bit 3-0 **RPnR<3:0>:** Peripheral Pin Select Output bits
See Table 11-2 for output pin selection values.

Note: Register values can only be changed if the Configuration bit, IOLOCK (CFGCON<13>), = 0.

REGISTER 19-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

bit 5 **ABAUD:** Auto-Baud Enable bit
1 = Enable baud rate measurement on the next character – requires reception of Sync character (0x55); cleared by hardware upon completion
0 = Baud rate measurement disabled or completed

bit 4 **RXINV:** Receive Polarity Inversion bit
1 = UxRX Idle state is '0'
0 = UxRX Idle state is '1'

bit 3 **BRGH:** High Baud Rate Enable bit
1 = High-Speed mode – 4x baud clock enabled
0 = Standard Speed mode – 16x baud clock enabled

bit 2-1 **PDSEL<1:0>:** Parity and Data Selection bits
11 = 9-bit data, no parity
10 = 8-bit data, odd parity
01 = 8-bit data, even parity
00 = 8-bit data, no parity

bit 0 **STSEL:** Stop Selection bit
1 = 2 Stop bits
0 = 1 Stop bit

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

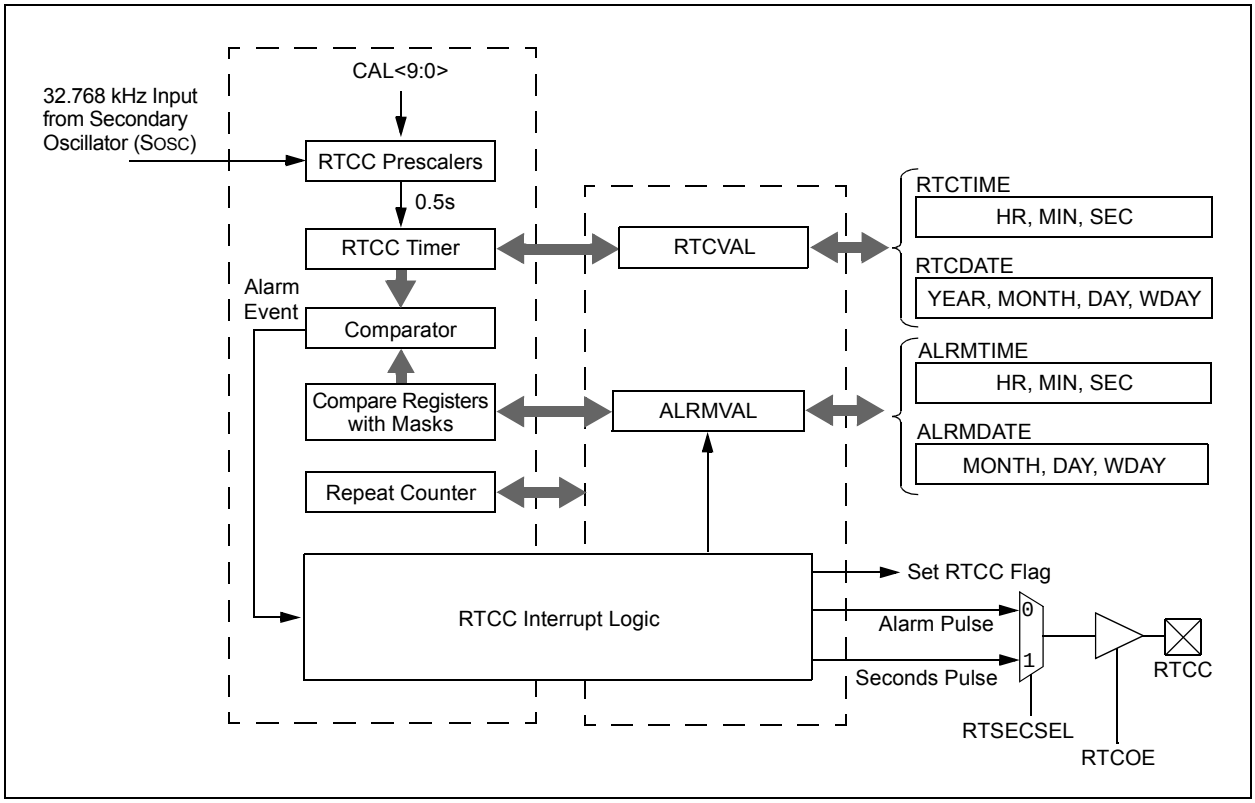
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS60001125), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

Following are some of the key features of this module:

- Time: hours, minutes and seconds
- 24-hour format (military time)
- Visibility of one-half second period
- Provides calendar: day, date, month and year
- Alarm intervals are configurable for half of a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month and one year
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat: Chime
- Year range: 2000 to 2099
- Leap year correction
- BCD format for smaller firmware overhead
- Optimized for long-term battery operation
- Fractional second synchronization
- User calibration of the clock crystal frequency with auto-adjust
- Calibration range: ±0.66 seconds error per month
- Calibrates up to 260 ppm of crystal error
- Requirements: External 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

FIGURE 21-1: RTCC BLOCK DIAGRAM



22.1 ADC Control Registers

TABLE 22-1: ADC REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9000	AD1CON1(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	FORM<2:0>			SSRC<2:0>			CLRASAM	—	ASAM	SAMP	DONE	0000
9010	AD1CON2(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	VCFG<2:0>			OFFCAL	—	CSCNA	—	—	BUFS	—	SMPI<3:0>				BUFM	ALTS	0000
9020	AD1CON3(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ADRC	—	—	SAMC<4:0>					ADCS<7:0>								0000
9040	AD1CHS(1)	31:16	CH0NB	—	—	—	CH0SB<3:0>				CH0NA	—	—	—	CH0SA<3:0>				0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
9050	AD1CSSL(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CSSL15	CSSL14	CSSL13	CSSL12	CSSL11	CSSL10	CSSL9	CSSL8	CSSL7	CSSL6	CSSL5	CSSL4	CSSL3	CSSL2	CSSL1	CSSL0	0000
9070	ADC1BUF0	31:16	ADC Result Word 0 (ADC1BUF0<31:0>)																0000
		15:0																	0000
9080	ADC1BUF1	31:16	ADC Result Word 1 (ADC1BUF1<31:0>)																0000
		15:0																	0000
9090	ADC1BUF2	31:16	ADC Result Word 2 (ADC1BUF2<31:0>)																0000
		15:0																	0000
90A0	ADC1BUF3	31:16	ADC Result Word 3 (ADC1BUF3<31:0>)																0000
		15:0																	0000
90B0	ADC1BUF4	31:16	ADC Result Word 4 (ADC1BUF4<31:0>)																0000
		15:0																	0000
90C0	ADC1BUF5	31:16	ADC Result Word 5 (ADC1BUF5<31:0>)																0000
		15:0																	0000
90D0	ADC1BUF6	31:16	ADC Result Word 6 (ADC1BUF6<31:0>)																0000
		15:0																	0000
90E0	ADC1BUF7	31:16	ADC Result Word 7 (ADC1BUF7<31:0>)																0000
		15:0																	0000
90F0	ADC1BUF8	31:16	ADC Result Word 8 (ADC1BUF8<31:0>)																0000
		15:0																	0000
9100	ADC1BUF9	31:16	ADC Result Word 9 (ADC1BUF9<31:0>)																0000
		15:0																	0000
9110	ADC1BUFA	31:16	ADC Result Word A (ADC1BUFA<31:0>)																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for details.

29.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

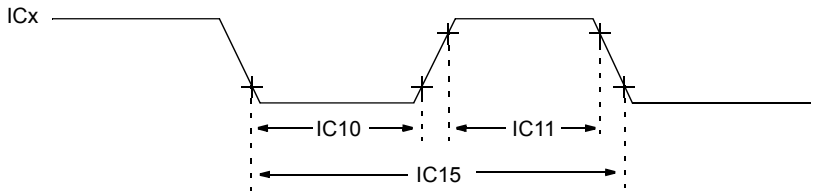
- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

TABLE 30-24: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**		**Min.**	**Max.**	**Units**	**Conditions**	
TB10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15	N = prescale value (1, 2, 4, 8, 16, 32, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15	
TB15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of [(25 ns or 2 TPB)/N] + 30 ns	—	ns	VDD > 2.7V	
				[(Greater of [(25 ns or 2 TPB)/N] + 50 ns	—	ns	VDD < 2.7V	
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	TPB	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-7: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



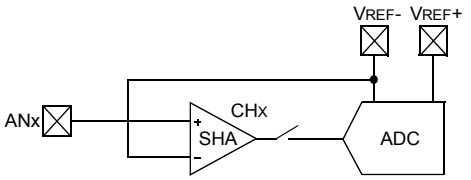
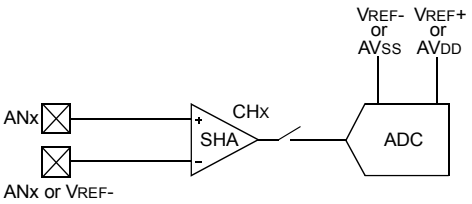
Note: Refer to Figure 30-1 for load conditions.

TABLE 30-25: INPUT CAPTURE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	TCCL	ICx Input Low Time	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	N = prescale value (1, 4, 16)
IC11	TCCH	ICx Input High Time	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	
IC15	TCCP	ICx Input Period	[(25 ns or 2 TPB)/N] + 50 ns	—	ns	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

TABLE 30-35: 10-BIT CONVERSION RATE PARAMETERS

AC CHARACTERISTICS(2)			Standard Operating Conditions (see Note 3): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
ADC Speed	**TAD Min.**	**Sampling Time Min.**	**RS Max.**	**VDD**	**ADC Channels Configuration**
1 Msps to 400 ksps(1)	65 ns	132 ns	500Ω	3.0V to 3.6V	
Up to 400 ksps	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	

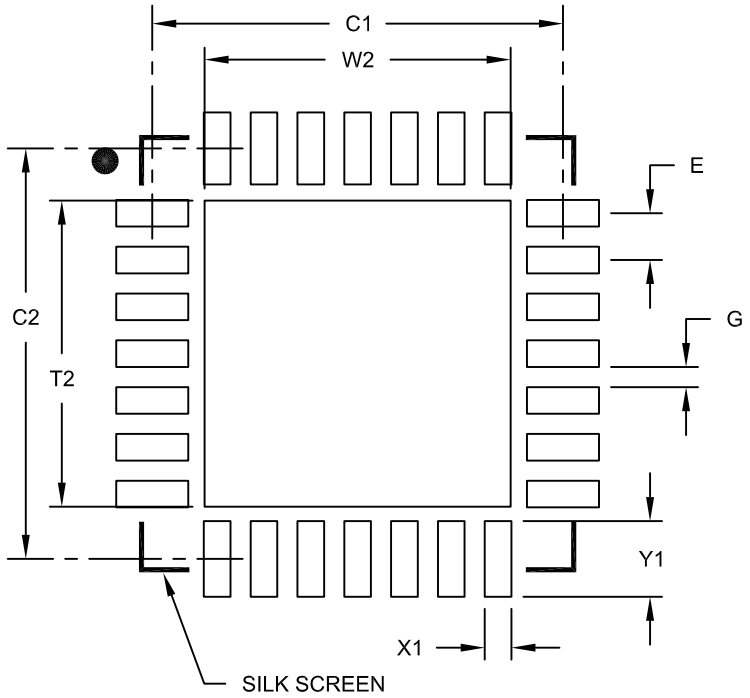
Note 1: External VREF- and VREF+ pins must be used for correct operation.

2: These parameters are characterized, but not tested in manufacturing.

3: The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

Notes:

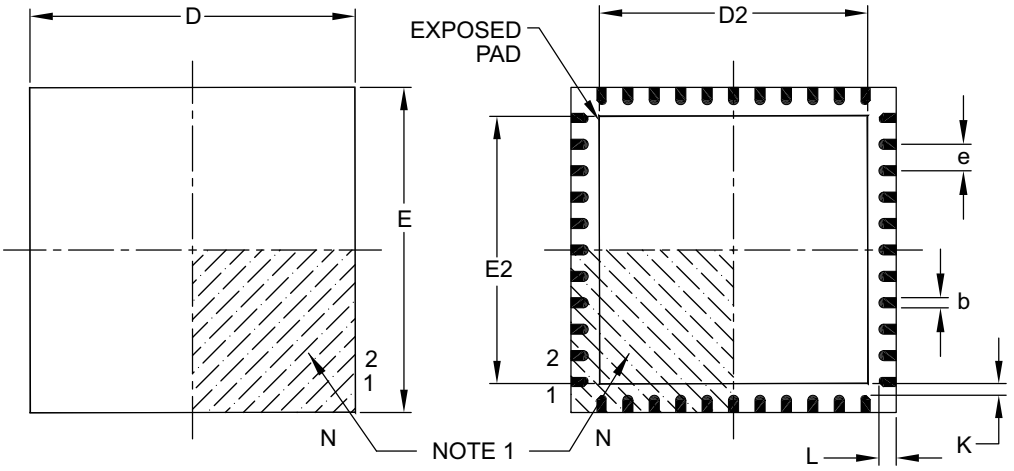
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

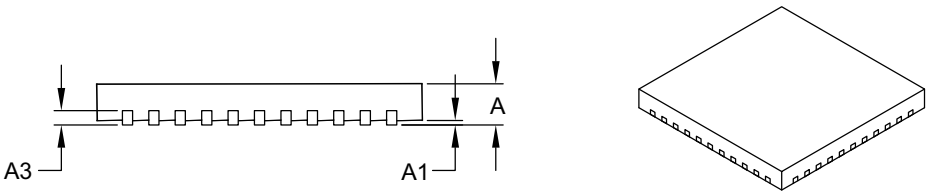
Microchip Technology Drawing No. C04-2105A

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW **BOTTOM VIEW**



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

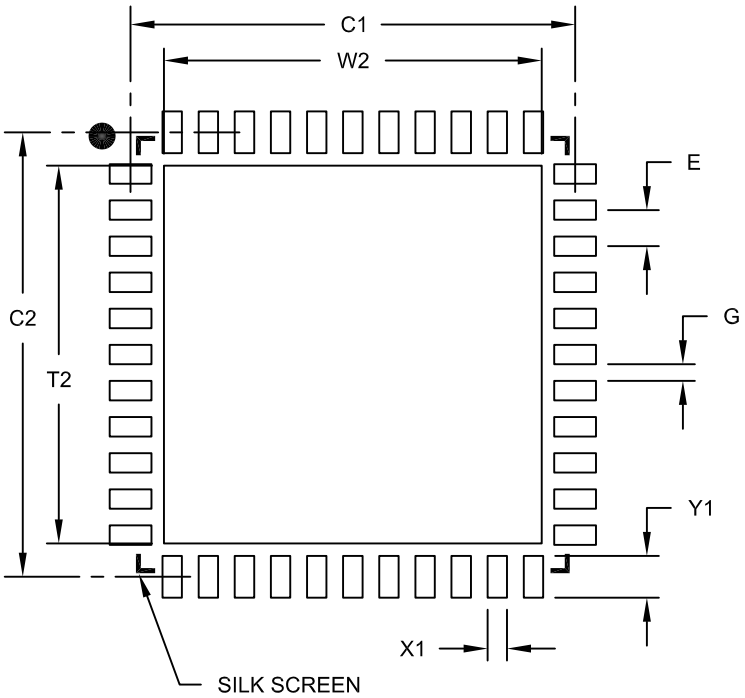
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			6.80
Optional Center Pad Length	T2			6.80
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.80
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A